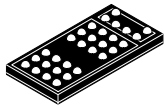


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

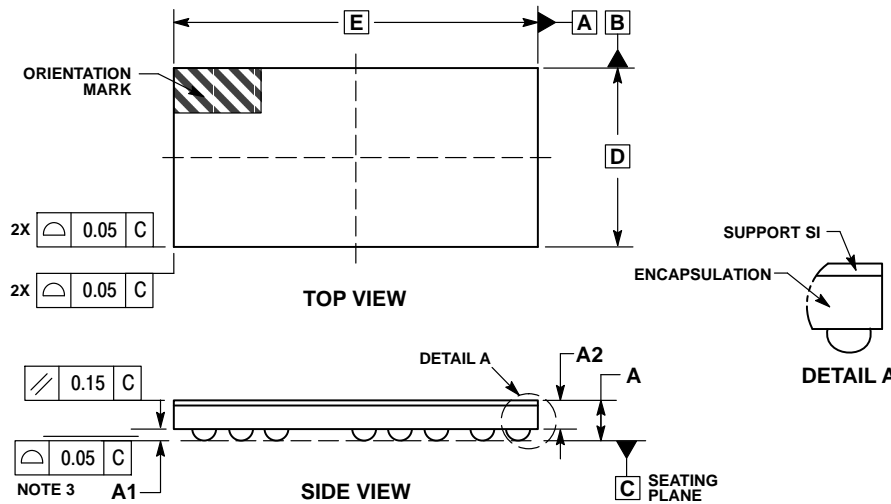
ON Semiconductor®



SCALE 4:1

ECP30, 1.97x4.01  
CASE 971BC  
ISSUE A

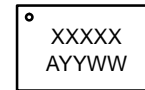
DATE 23 FEB 2016



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
  4. DIMENSION b IS MEASURED AT THE MAXIMUM BALL DIAMETER PARALLEL TO DATUM C.

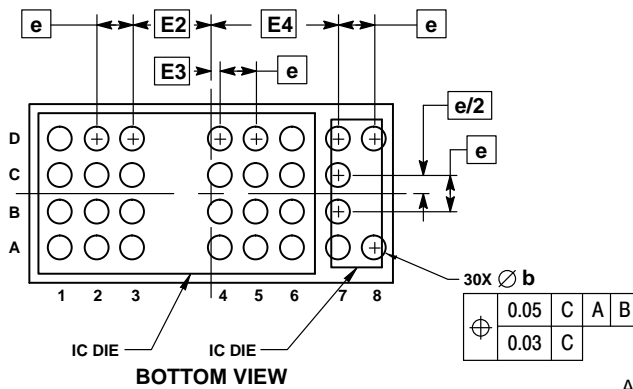
DIM	MILLIMETERS	
	MIN	MAX
A	0.545	0.625
A1	0.165	0.205
A2	0.380	0.420
b	0.245	0.285
D	1.970 BSC	
E	4.010 BSC	
E2	0.860 BSC	
E3	0.100 BSC	
E4	1.405 BSC	
e	0.400 BSC	

### GENERIC MARKING DIAGRAM\*

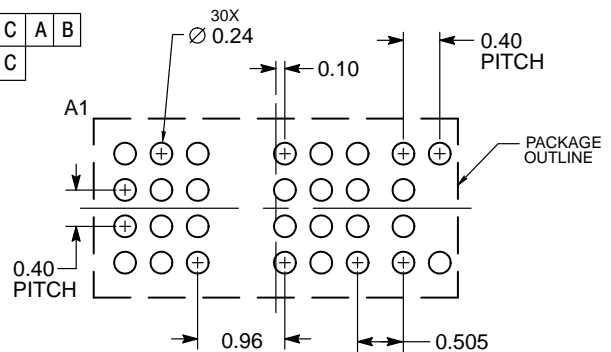


A = Assembly Location  
YY = Year  
WW = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.



### RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON05189G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
REFERENCE:		
DESCRIPTION:	ECP30, 1.97X4.01	PAGE 1 OF 2

